

REMARKS

Claims 1-7 and 12-25 are pending in the present application. Claims 1 and 7 have been amended. Claims 12-25 have been presented herewith. Claims 5 and 6 have been withdrawn from consideration as being directed to a non-elected invention. Also, claims 8-11 have been canceled. Applicant reserves the right to file a divisional application including the non-elected claims.

Priority Under 35 U.S.C. 119

Applicant notes the Examiner's acknowledgment of the Claim for Priority under 35 U.S.C. 119, and receipt of the certified copy of the Priority Document.

Drawings

Applicant notes the Examiner's acceptance of the drawings as filed along with the present application on February 11, 2004.

Enclosed is one (1) red-inked drawing Annotated Sheet, wherein Fig. 1 has been corrected so that the side surface of semiconductor chip 5 is denoted as 56, as described on page 11, line 26 through to page 12, line 1 of the present application. Also enclosed is one (1) drawing Replacement Sheet, incorporating the above noted drawing correction. **The Examiner is respectfully requested to acknowledge receipt and acceptance of the drawing Replacement Sheet.**

Claim Rejections-35 U.S.C. 103

Claims 1-4 and 7 have been rejected under 35 U.S.C. 103(a) as being unpatentable over the De Givry reference (U.S. Patent No. 5,229,960) in view of the Fukui et al. reference (U.S. Patent No. 6,100,594). This rejection, insofar as it may pertain to the presently pending claims, is traversed for the following reasons.

The semiconductor device of claim 1 includes in combination a die pad section; a first semiconductor chip; a second semiconductor chip; a support member; lead terminal sections; and a resin encapsulating body, "wherein a first side surface of the support member is located directly under the second semiconductor chip, and a second side surface of the support member opposite the first side surface is located out from under the second semiconductor chip". Applicant respectfully submits that the semiconductor device of claim 1 would not have been obvious in view of the prior art as relied upon by the Examiner.

The Examiner has relied upon Figs. 1 and 2 of the De Givry reference, interpreting memory chips 14 and 16 respectively as the first and second semiconductor chips of claim 1, a portion of supporting substrate 12 as the die pad section of claim 1, and support block 20 as the support member of claim 1. However, as may be readily understood in view of Fig. 1 of the De Givry reference in particular, support block 20 is disposed so as to be located entirely under memory chip 16. Support block 20 in Figs. 1 and 2 of the De Givry reference does not have a first side surface located directly under a second semiconductor chip, and a second side surface

opposite the first side surface thereof that is located out from under the second semiconductor chip, as would be necessary to meet the features of claim 1. The Fukui et al. reference as relied upon by the Examiner does not include a support block or support member, and thus does not overcome the above noted deficiencies of the De Givry reference. Applicant therefore respectfully submits that the semiconductor device of claim 1 would not have been obvious in view of the prior art as relied upon by the Examiner taken singularly or together, and that this rejection, insofar as it may pertain to claims 1-4 and 7, is improper for at least these reasons.

Claim 7 features that the surface of the second semiconductor chip has third and fourth sides opposite to each other, and "the fourth side thereof is located directly above the support member". As noted above, since support block 20 of the De Givry reference is located entirely under memory chip 16, memory chip 16 does not include a side thereof that is located directly above support block 20, as would be necessary to meet the features of claim 7. The Fukui et al. reference as relied upon by the Examiner does not overcome these deficiencies of the De Givry reference. Applicant therefore respectfully submits that the semiconductor device of claim 7 would not have been obvious in view of the prior art as relied upon by the Examiner taken singularly or together, and that this rejection of claim 7 is improper for at least these additional reasons.

Claims 5 and 6

The Examiner is respectfully requested to rejoin withdrawn claims 5 and 6, which as dependent upon claim 1 should distinguish over the relied upon prior art and be allowable for at least the same reasons as set forth above with respect to claim 1.

Claims 12-25

Applicant respectfully submits that claims 12-25 are readable on elected Species embodiment 1: Figs. 1-7.

Applicant respectfully submits that claims 12-18 should be allowable at least by virtue of dependency upon claim 1, and by further reason of the features therein. With further regard to claim 12, memory chips 14 and 16 in Fig. 1 of the De Givry reference do not "extend in a same first direction so as to be disposed in parallel with respect to each other". With further regard to claim 13, support block 20 in Fig. 1 of the De Givry reference does not have a first side surface that is in direct contact with the side surface of memory chip 14. With further regard to claim 15, memory chip 14 in Fig. 1 of the De Givry reference does not have a portion of a back surface thereof that is fixed to inner portions of lead terminal sections. That is, tabs 18 of memory chip 14 as shown in Fig. 1 of the De Givry reference are described as connected to tracks formed on supporting substrate 12 by flexible wires 19.

The semiconductor device of claim 19 includes in combination a lead frame "including a die pad section and lead terminal sections"; a first semiconductor chip; a

second semiconductor chip; a support member "having a surface fixed to the back surface of the second semiconductor chip and a back surface fixed to the die pad section and first portions of the lead terminal sections"; wirings; and a resin encapsulating body. Applicant respectfully submits that memory chip 14 in Figs. 1 and 2 of the De Givry reference is not disclosed as having a lead frame including a die pad section and lead terminal sections, and is not disclosed as having a back surface that is fixed to a die pad section and first portions of lead terminal sections, as would be necessary to meet the features of claim 19. The Fukui et al. reference as relied upon by the Examiner does not overcome these deficiencies of the DeGivry reference. Applicant therefore respectfully submits that the semiconductor device of claim 19 distinguishes over and would not have been obvious in view of the prior art as relied upon by the Examiner taken singularly or together, and that claims 19-25 should thus be allowable.

Conclusion

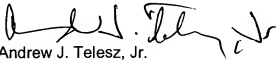
The Examiner is respectfully requested to reconsider and withdraw the corresponding rejection, and to pass the claims of the present application to issue for at least the above reasons.

In the event that there are any outstanding matters remaining in the present application, please contact Andrew J. Telesz, Jr. (Reg. No. 33,581) at (571) 283-0720 in the Washington, D.C. area, to discuss these matters.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment for any additional fees that may be required, or credit any overpayment, to Deposit Account No. 50-0238.

Respectfully submitted,

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Enclosures: One (1) drawing Annotated Sheet
One (1) drawing Replacement Sheet

